

# Main Logic board and PCA redesign projects

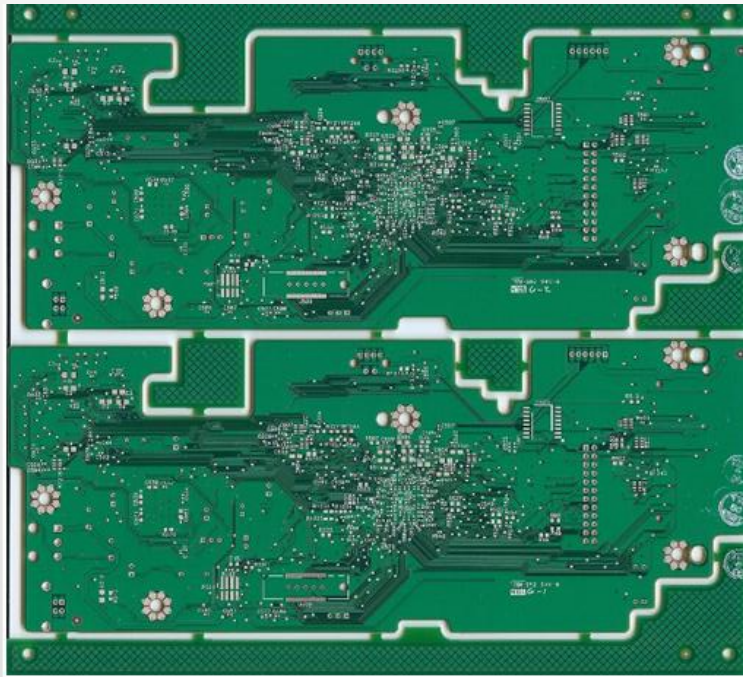
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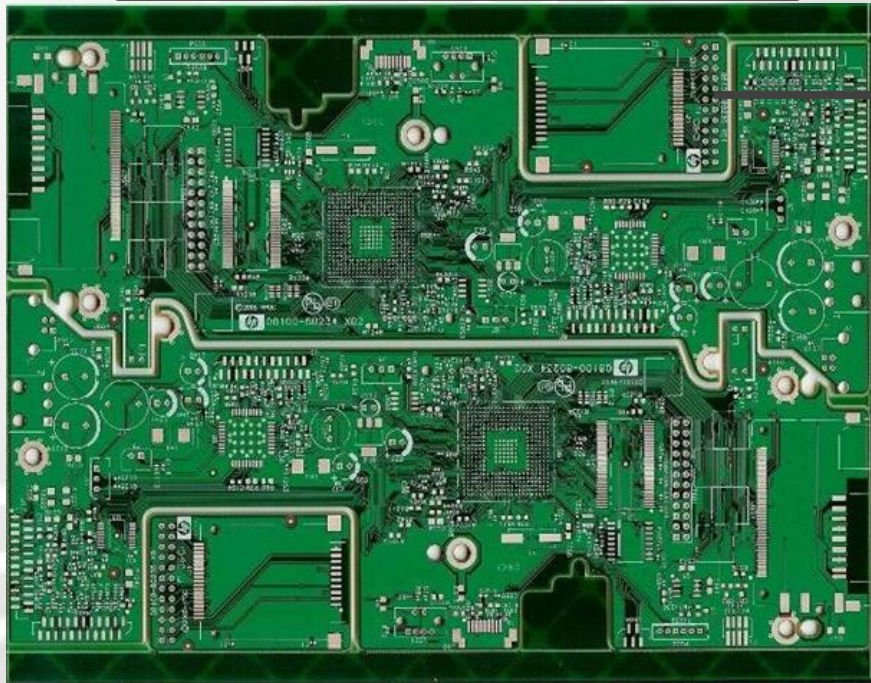
# Main Logic PCA redesign nesting of Photo card | \$5M in savings



Original design and panel



Cost reduced Design and Panel



4-layer Photo card PCB nested

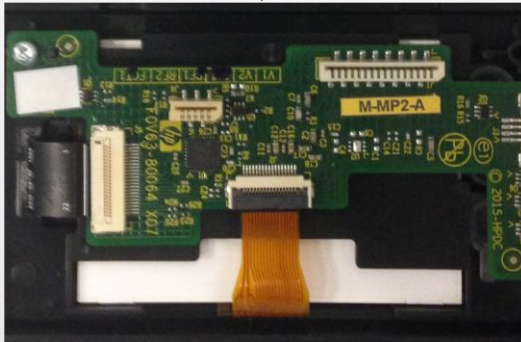


# Control panel PCA Redesign | \$1.32M in savings

Optimize Control panel PCB | 0.16/unit

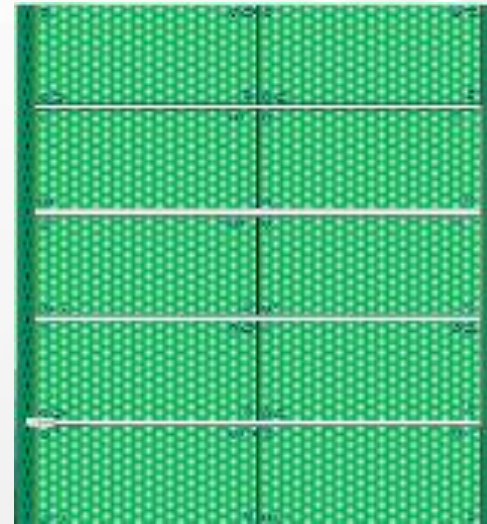


Original CP design



Cost reduced Design

PCB Panel produces 16 PCBs coCMred to 10 before



Original Design



Cost reduced Design

Cost reduced control panel used on multiple programs generating \$1.32M in savings

# Component savings and optimization for cost

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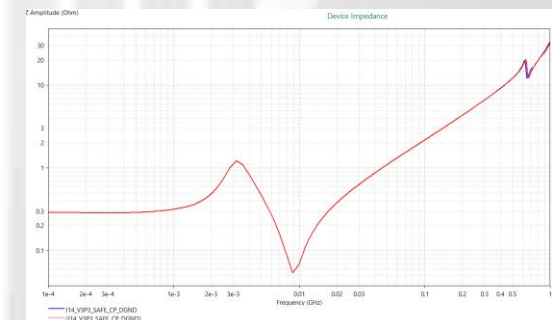
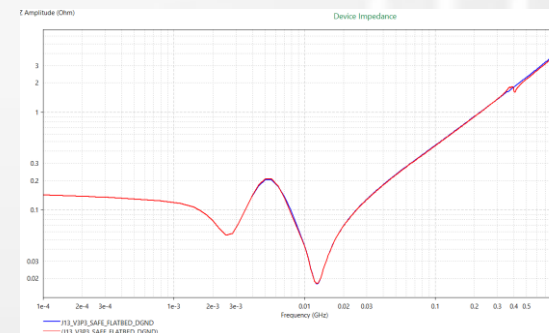
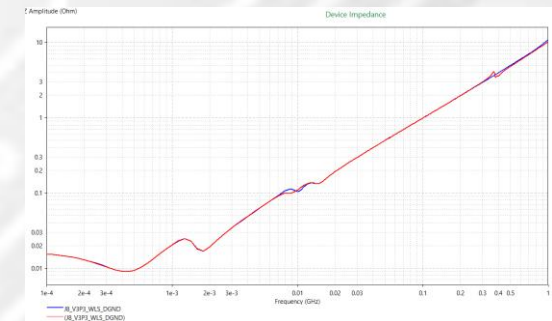
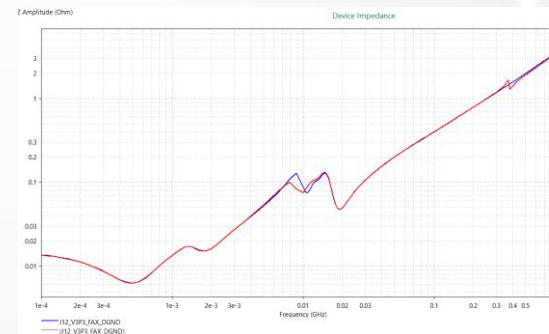
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# Decoupling Capacitor EMC Optimization and Removal | \$5M in savings



Impedance simulation using Cadence Sigrity tool

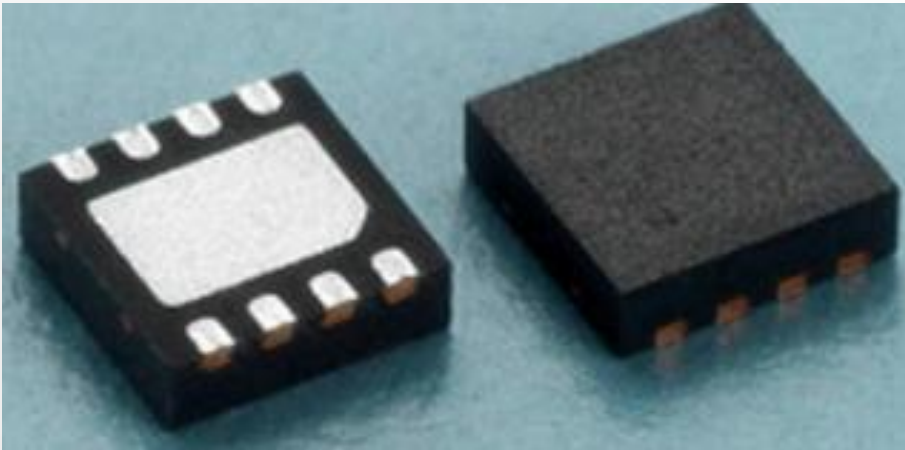
|      |   |
|------|---|
| C299 | located along PCB edge                      |
| C301 | located along PCB edge                      |
| C303 | located along PCB edge                      |
| C304 | located along PCB edge                      |
| C307 | located along PCB edge                      |
| C308 | located along PCB edge                      |
| C335 | located along PCB edge                      |
| C339 | located along PCB edge                      |
| C797 | Under U101, Impedance plot is quite similar |
| C24  | Under U1, Impedance plot is quite similar   |



— Original Simulation:  
— Removed caps Simulation:

# Change package on Pen security chip DFN-8 to SO-8 | \$2 M in savings

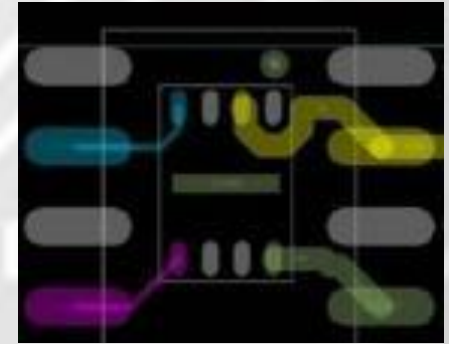
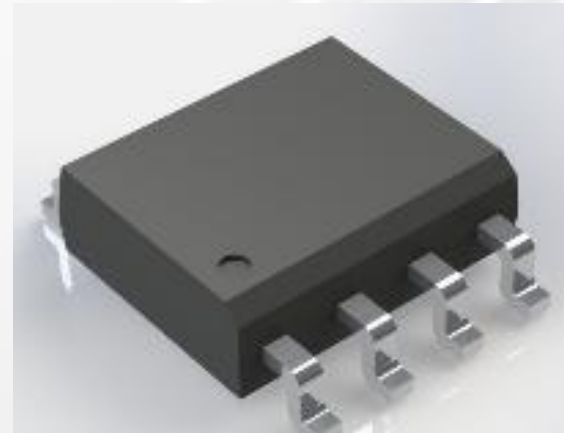
**DFN Package Pen Security Acumen Chip**



Change DFN to So8



**10 cent cheaper : 8 Pin SO-8 package**



Overlap nesting DFN to SO8 geometry in Layout on multiple programs, qualified and ECO design change into production

Collaborated with ST to redesign the security chip package, transitioning from DFN8 (Dual Flat No Leads) to SO8 (Small Outline-Leads). Successfully qualified across multiple programs, achieving a cost reduction of \$0.10 per unit, resulting in total savings of \$2M over two years.

# Process improvement for Savings

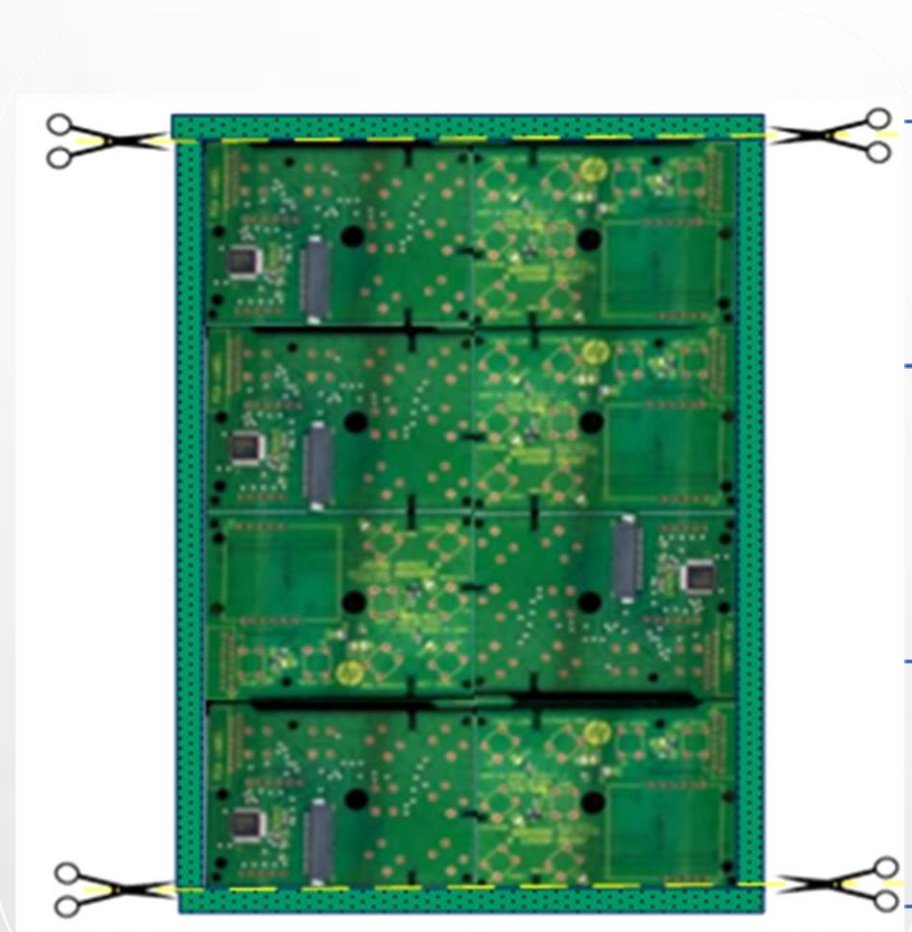
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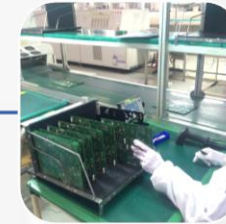




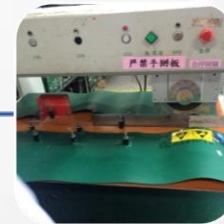
# 4 Tab to 2 Tab Panel Conversion Factory process change | \$1M /year savings



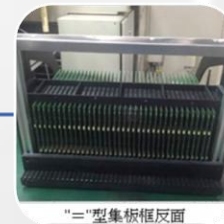
Extra Tabs on PCB's Increase Per PCB cost to HP



"4 side tabs PCBs" used in Production due to Foxconn process and fixture limitations



Design for supply chain team engaged with Foxconn and CDPS to understand their Fixtures and process



Process Improvement and fixture redesign with Foxconn to run production with "2 side tab" PCB's

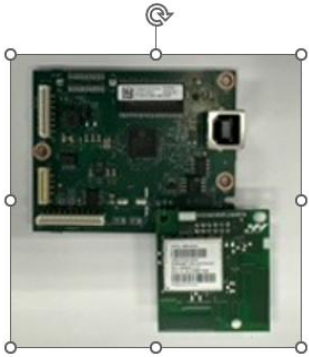


Estimated minimum \$500K+ savings year after year at Foxconn from 2 Tab PCB's

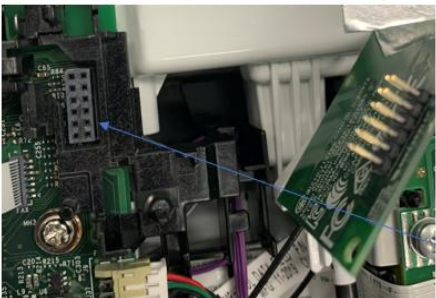


# Direct solder wifi Card to Main PCA

## Direct solder wi-fi card to the mainboard



Inkjet business 100% direct solders wi-fi card



Remove plugin connector for WI-FI card on LaserJet products by direct soldering Wi-fi card into the main PCA

